

LNPT[™] THERMOCOMP[™] COMPOUND MB006S

MB-1006 HS

REGION AMERICAS

DESCRIPTION

LNP THERMOCOMP MB006S compound is based on Polypropylene (PP) resin containing 30% glass bead. Added features of this grade include: Heat Stabilized.

GENERAL INFORMATION	
Features	Heat Stabilized, Low Warpage, High stiffness/Strength, No PFAS intentionally added
Fillers	Glass Bead
Polymer Types	Polypropylene, Unspecified (PP, Unspecified)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Water Management
Consumer	Sport/Leisure, Personal Accessory
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, yield	24	MPa	ASTM D638
Tensile Stress, break	19	MPa	ASTM D638
Tensile Strain, yield	6.3	%	ASTM D638
Tensile Strain, break	87.5	%	ASTM D638
Flexural Stress	44	MPa	ASTM D790
Flexural modulus	2130	MPa	ASTM D790
Tensile Stress, yield	24	MPa	ISO 527
Tensile Stress, break	19	MPa	ISO 527
Tensile Strain, yield	5.5	%	ISO 527
Tensile Strain, break	83.4	%	ISO 527
Tensile Modulus, 1 mm/min	2400	MPa	ISO 527
Flexural Stress	46	MPa	ISO 178
Flexural Modulus	2900	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	234	J/m	ASTM D4812
Izod Impact, notched, 23°C	21	J/m	ASTM D256
Instrumented Dart Impact Energy @ peak, 23°C	3	J	ASTM D3763
Multiaxial Impact	1	J	ISO 6603
Izod Impact, unnotched 80*10*4 +23°C	20	kJ/m ²	ISO 180/1U

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Izod Impact, notched 80*10*4 +23°C	2	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT, 0.45 MPa, 3.2 mm, unannealed	112	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	70	°C	ASTM D648
CTE, -40°C to 40°C, flow	6.89E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, xflow	7.E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, flow	6.88E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	7.E-05	1/°C	ISO 11359-2
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	75	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Density	1.12	g/cm ³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.02	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	1.2	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	1.1	%	ASTM D955
Mold Shrinkage, flow, 24 hrs ⁽²⁾	1.16	%	ISO 294
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	1.15	%	ISO 294
Density	1.11	g/cm ³	ISO 1183
INJECTION MOLDING ⁽³⁾			
Drying Temperature	80	°C	
Drying Time	4	Hrs	
Melt Temperature	225 – 250	°C	
Front - Zone 3 Temperature	240 – 250	°C	
Middle - Zone 2 Temperature	215 – 225	°C	
Rear - Zone 1 Temperature	195 – 205	°C	
Mold Temperature	30 – 50	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

DISCLAIMER

Any sale by SABIC, its subsidiaries and affiliates (each a "seller"), is made exclusively under seller's standard conditions of sale (available upon request) unless agreed otherwise in writing and signed on behalf of the seller. While the information contained herein is given in good faith, SELLER MAKES NO WARRANTY, EXPRESS OR IMPLIED, INCLUDING MERCHANTABILITY AND NONINFRINGEMENT OF INTELLECTUAL PROPERTY, NOR ASSUMES ANY LIABILITY, DIRECT OR INDIRECT, WITH RESPECT TO THE PERFORMANCE, SUITABILITY OR FITNESS FOR INTENDED USE OR PURPOSE OF THESE PRODUCTS IN ANY APPLICATION. Each customer must determine the suitability of seller materials for the customer's particular use through appropriate testing and analysis. No statement by seller concerning a possible use of any product, service or design is intended, or should be construed, to grant any license under any patent or other intellectual property right.